

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China









3.0x1.0 mm SMD CHIP LED LAMP

PRELIMINARY SPEC

Part Number: APECVA3010MGC

Mega Green

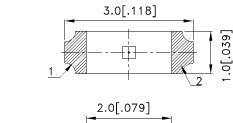
Features

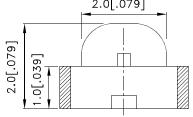
- 3.0mmx1.0mm SMT LED, 2.0mm thickness.
- Low power consumption.
- Wide viewing angle.
- Ideal for back light and indicator.
- Package: 2000pcs / reel.
- Moisture sensitivity level : level 3.
- RoHS compliant.

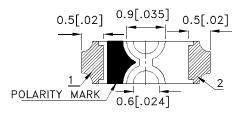
Description

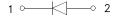
The Mega Green source color devices are made with AlGaInP on GaAs substrate Light Emitting Diode.

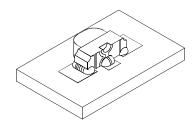
Package Dimensions











- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is ±0.15(0.006") unless otherwise noted.
- 3. Specifications are subject to change without notice.4. The device has a single mounting surface. The device must be mounted according to the specifications.





SPEC NO: DSAJ1857 **REV NO: V.1** DATE: MAR/19/2009 PAGE: 1 OF 5 APPROVED: WYNEC **CHECKED: Allen Liu** DRAWN: S.P.Chen ERP: 1203009112

Selection Guide

Part No.	Dice	Iv (mcd) [2] Dice		,	Viewing Angle [1]
		21	Min.	Тур.	201/2
APECVA3010MGC	Mega Green (AlGaInP)	WATER CLEAR	36	80	120°

- 1. 01/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value. 2. Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Mega Green	574		nm	IF=20mA
λD [1]	Dominant Wavelength	Mega Green	570		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	Mega Green	26		nm	IF=20mA
С	Capacitance	Mega Green	20		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Mega Green	2.1	2.5	V	IF=20mA
lR	Reverse Current	Mega Green		10	uA	V _R =5V

Notes:

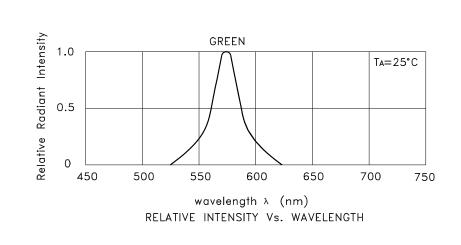
1.Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V.

Absolute Maximum Ratings at TA=25°C

Parameter Mega Green		Units	
Power dissipation	75	mW	
DC Forward Current	30	mA	
Peak Forward Current [1]	150	mA	
Reverse Voltage	5	V	
Operating Temperature	-40°C To +85°C		
Storage Temperature	-40°C To +85°C		

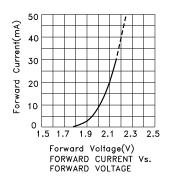
Note: 1. 1/10 Duty Cycle, 0.1ms Pulse Width.

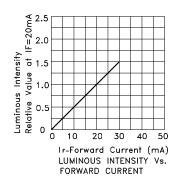
SPEC NO: DSAJ1857 **REV NO: V.1** DATE: MAR/19/2009 PAGE: 2 OF 5 APPROVED: WYNEC **CHECKED: Allen Liu** DRAWN: S.P.Chen ERP: 1203009112

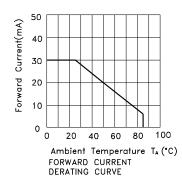


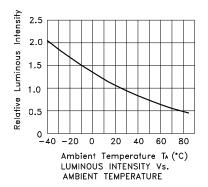
Mega Green

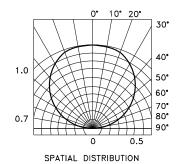
APECVA3010MGC











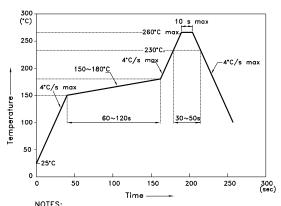
 SPEC NO: DSAJ1857
 REV NO: V.1
 DATE: MAR/19/2009
 PAGE: 3 OF 5

 APPROVED: WYNEC
 CHECKED: Allen Liu
 DRAWN: S.P.Chen
 ERP: 1203009112

APECVA3010MGC

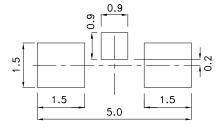
Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process.

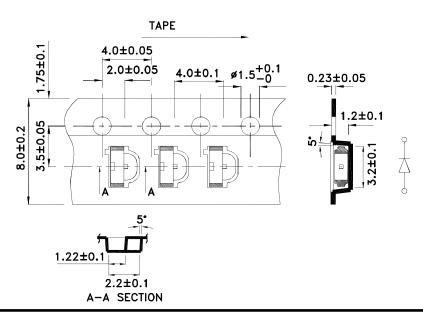


NOTES: 1.We recommend the reflow temperature 245°C(+/-5°C).The maximum soldering temperature should be limited to 260°C. 2.Don't cause stress to the epoxy resin while it is exposed to high temperature.
 3.Number of reflow process shall be 2 times or less.

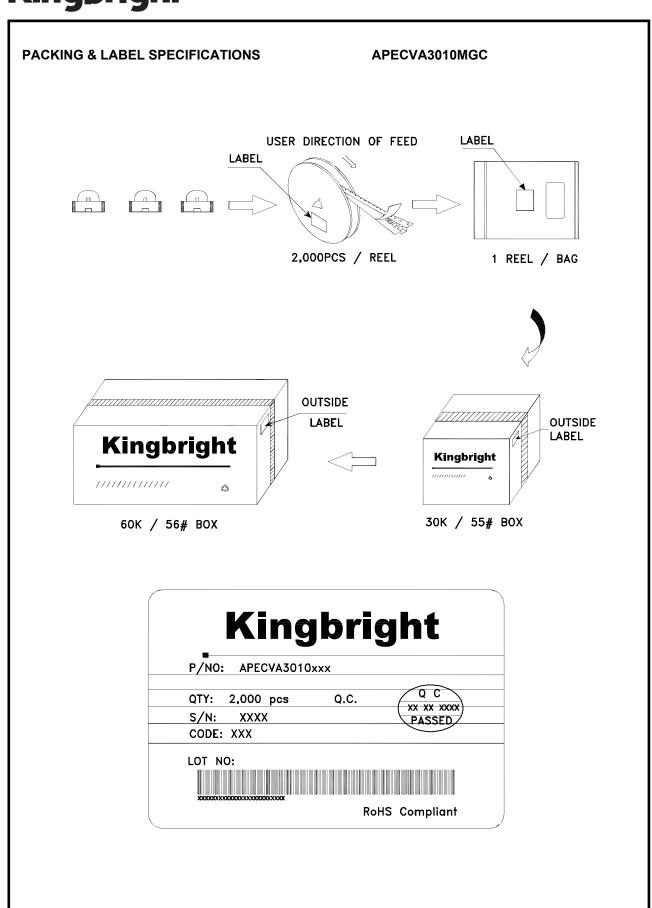
Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)



Tape Dimensions (Units: mm)



SPEC NO: DSAJ1857 **REV NO: V.1 DATE: MAR/19/2009** PAGE: 4 OF 5 **APPROVED: WYNEC CHECKED: Allen Liu** DRAWN: S.P.Chen ERP: 1203009112



SPEC NO: DSAJ1857 APPROVED: WYNEC REV NO: V.1 CHECKED: Allen Liu DATE: MAR/19/2009 DRAWN: S.P.Chen PAGE: 5 OF 5 ERP: 1203009112